1. Disassembly Procedures

S1 Turn off the monitor.

S2 Place the monitor on a soft cloth or cushion.

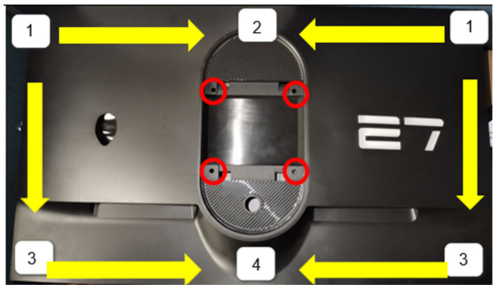
Press and hold the stand release button at the back of the display.

S3 Lift the stand assembly up and away from the monitor.

S4 Unlock 4 screws on Rear Cover

Use hands or scraper bar to disassemble “Rear Cover” from monitor

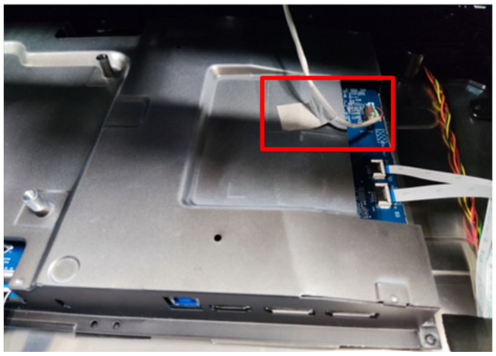
Notice the disassembly order:
Top Side=> Right / Left Side =>Bottom Side



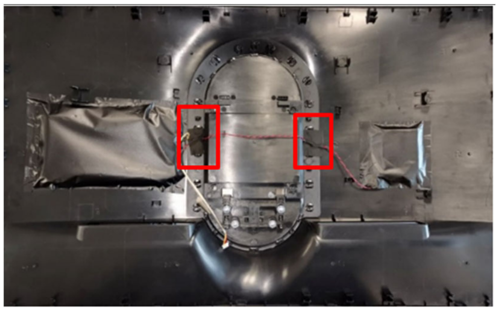
(Screw Torque: 8-10 kgf)

S5 Tear off conductive cloth tape from Main SHD

Unplug “WIRE 6/4/4P” from I/F BD to take off “Rear Cover “

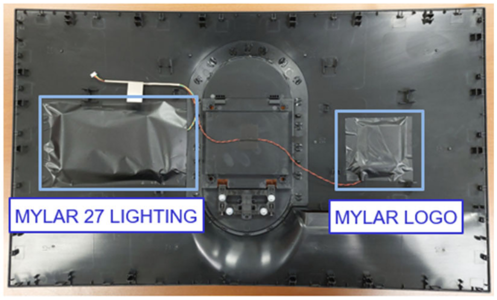


S6 Tear off 2 acetate tapes from “WIRE 6/4/4P” on Rear Cover

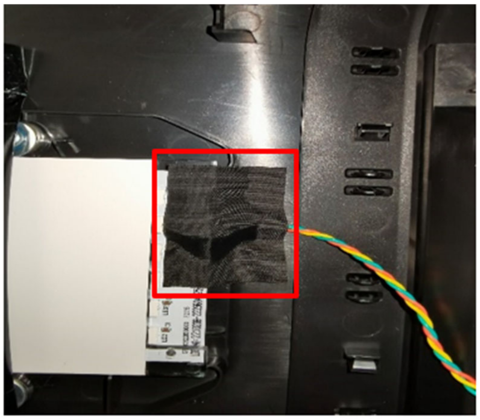


S7 Tear off “MYLAR 27 LIGHTING” from Rear Cover

Tear off “MYLAR LOGO” from Rear Cover



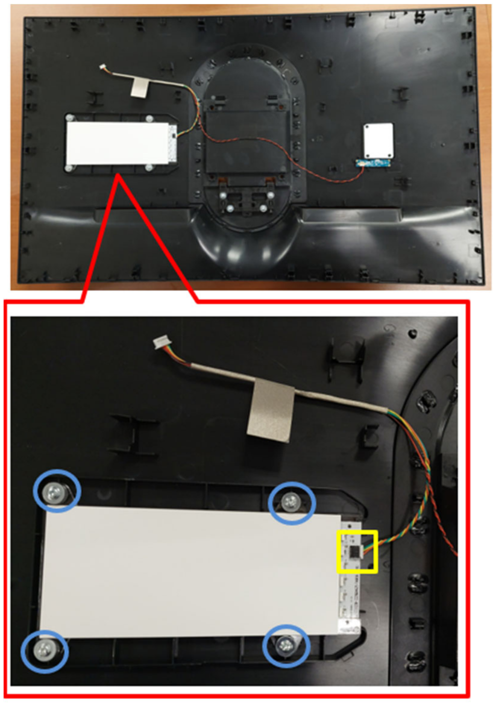
S8 Tear off acetate tape from the connector of “ASSY LED MOUDLE”



S9 Unlock 4 screws on “ASSY LED MOUDLE”

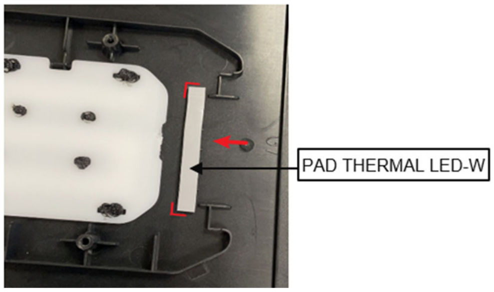
Disassemble “ASSY LED MOUDLE” from Rear Cover

Unplug “WIRE 6/4/4P” from “ASSY LED MOUDLE”



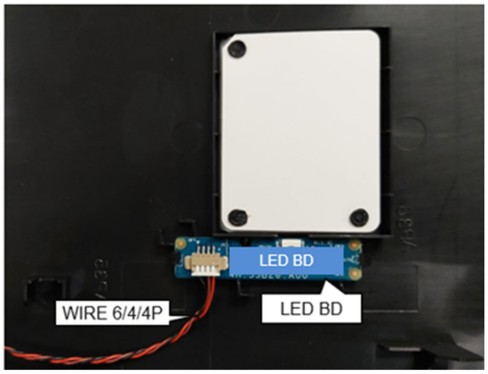
(Screw Torque: 4.5±0.5 kgf)

S10 Tear off “PAD THERMAL LED-W” from Rear Cover



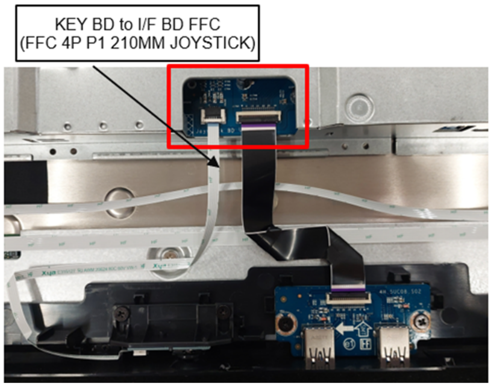
S11 Unplug “WIRE 6/4/4P” from “LED BD”

Disassemble “LED BD” from Rear Cover



S12 Unplug “KEY BD to I/F BD FFC” from I/F BD

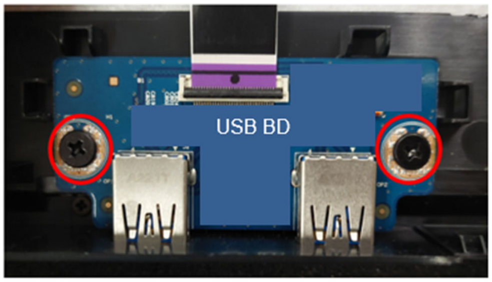
Unplug “FFC USB3 30/30” from I/F BD



S13 Unlock 2 screws on USB BD

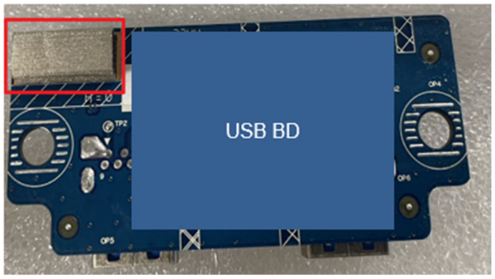
Disassemble USB BD from Middle Frame

Unplug "FFC USB3 30/30" from USB BD



(Screw Torque: 4.5±0.5 kgf)

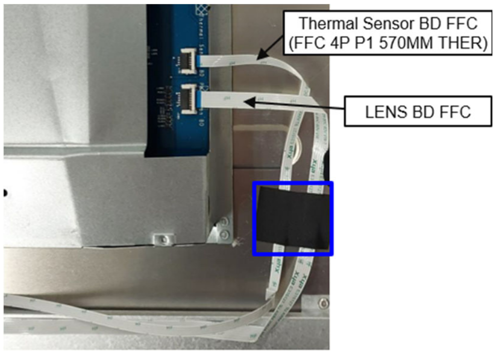
S14 Tear off a gasket from USB BD



S15 Tear off a tape from "LENS BD FFC" and "Thermal Sensor BD FFC" on Panel

Unplug "Thermal Sensor BD FFC" from I/F BD and tear off it from Panel

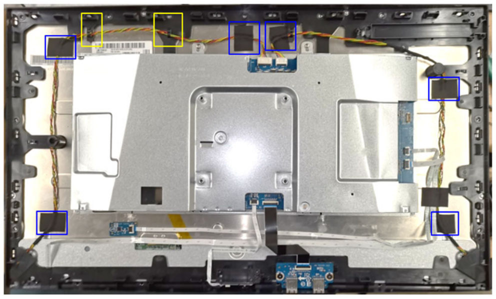
Unplug "LENS BD FFC" from I/F BD and tear off it from Panel



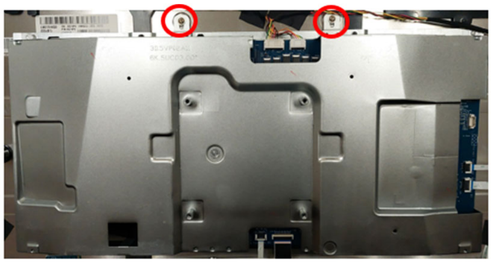
S16 Tear off 6 tapes from the backlight wires on panel (See blue mark)

Unplug "Short Backlight Wire" from I/F BD

Unplug "Long Backlight Wire" from I/F BD, then, disassemble it from the hooks on the upper left of Middle Frame (See yellow mark)



S17 Unlock 2 screws to disassemble "Main SHD" from Panel

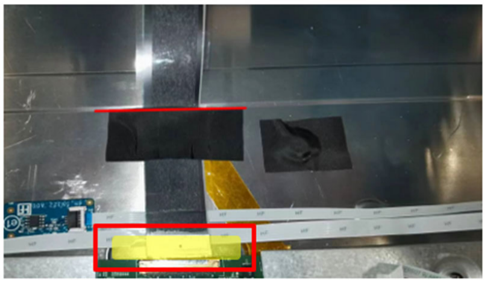


(Screw Torque: 4.5±0.5 kgf)

S18 Tear off an acetate tape and a yellow tape from "FFC EDP" on panel

Unplug "FFC EDP" from panel

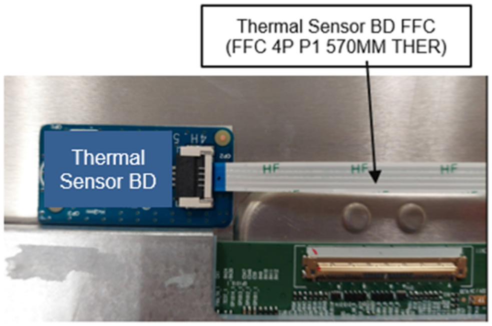
Take off "Main SHD" from Panel



S19 Tear off “Thermal Sensor BD FFC” from Panel

Unplug “Thermal Sensor BD FFC” from “Thermal Sensor BD”

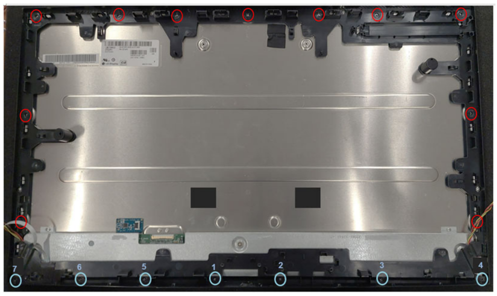
Disassemble “Thermal Sensor BD” from Panel



S20 Unlock 7 screws to disassemble Middle Frame and “ASSY BKT CHIN” (See blue marks)

Unlock 11 screws to disassemble Middle Frame and Panel (See red mark)

Disassemble Middle Frame from “ASSY BKT CHIN” and Panel

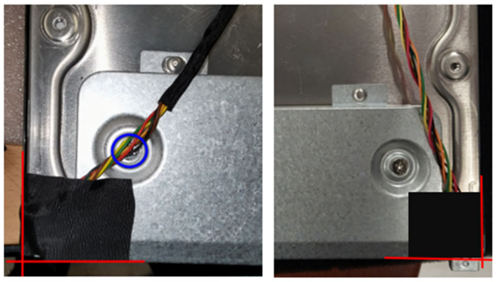


(Screw Torque-MF to Chin: 2.0±0.5 kgf)

(Screw Torque MF to panel: 4.5±0.5 kgf)

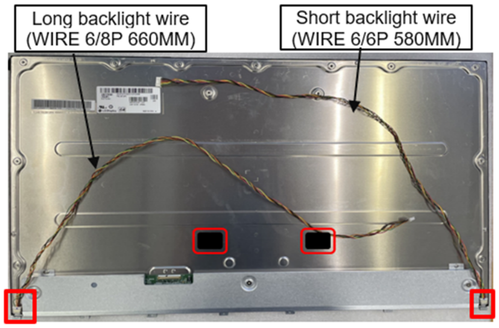
S21 Disassemble “ASSY BKT CHIN” from panel

S22 Tear off 2 acetate tapes from the connectors of backlight on panel



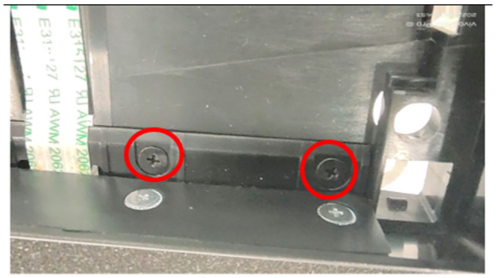
S23 Tear off 2 acetate tapes from two convex hulls at the bottom of the panel

Unplug long backlight wire and short backlight wire from panel



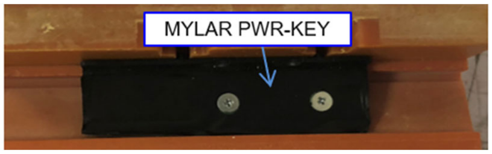
S24 Tear off “LENS BD FFC” from Middle Frame

Unlock 2 screws to disassemble Power Button module from Middle Frame

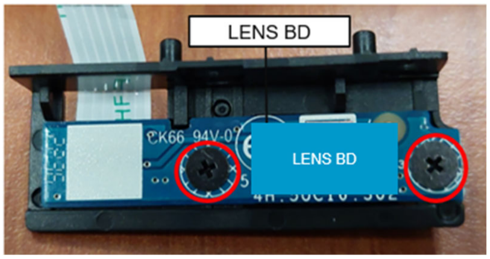


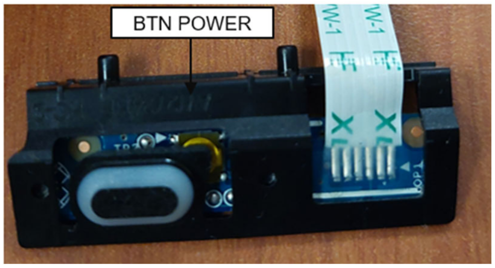
(Screw Torque: 1~1.1 kgf)

S25 Tear off “MYLAR PWR-KEY” from “LENS BD”



S26 Unlock 2 screws to disassemble “LENS BD” from “BTN POWER”

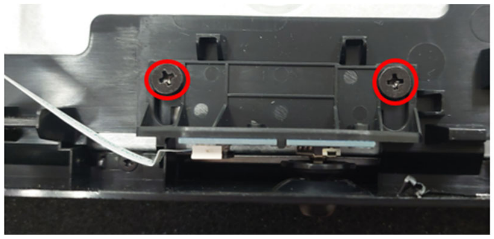




(Screw Torque: 1±0.05 kgf)

S27 Unlock 2 screws to disassemble “HOLDER L” from Middle Frame

Take off “HOLDER L” from Middle Frame

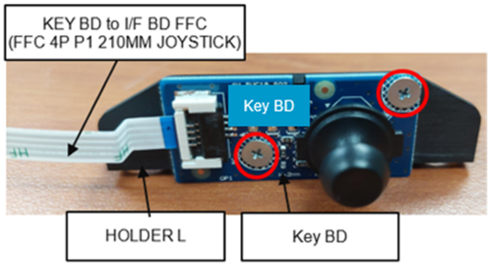


(Screw Torque: 4~5 kgf)

S28 Unlock 2 screws to disassemble “Key BD” from “HOLDER L”

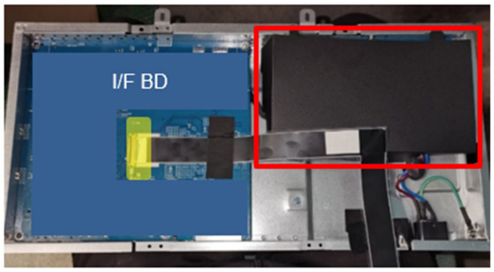
Take off “Key BD” from “HOLDER L”

Unplug “Key BD to I/F BD FFC” from “Key BD”

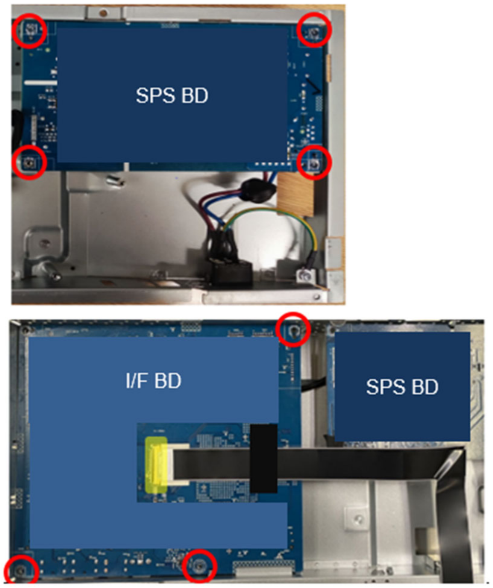


(Screw Torque: 1.8~2.0 kgf)

S29 Disassemble “MYLAR PWR” from Main SHD

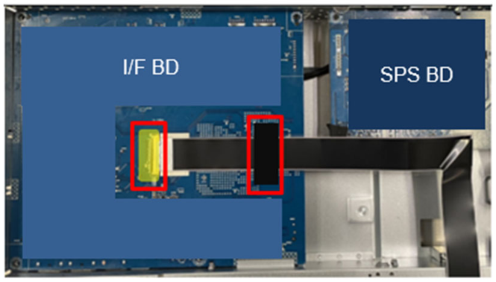


S30 Unlock 7 PCBA screws



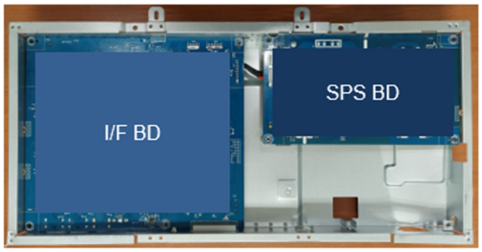
(Screw Torque: 8.5±1 kgf)

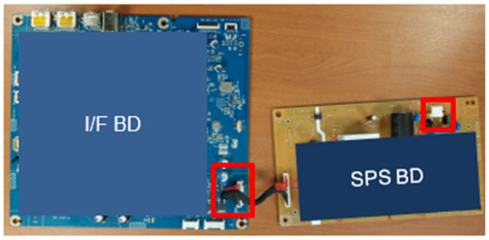
S31 Tear off an acetate tape and a yellow tape from “FFC EDP” on I/F BD, then, unplug “FFC EDP” from I/F BD



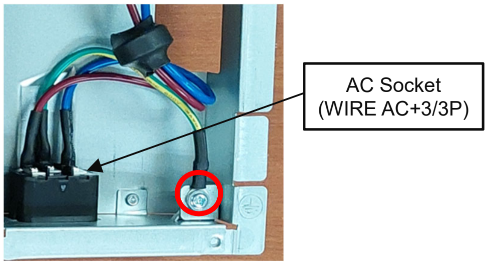
S32 Disassemble I/F BD from Main SHD and unplug “SPS BD to IF BD Wire” from I/F BD

Disassemble SPS BD from Main SHD and unplug “WIRE AC+3/3P” from SPS BD



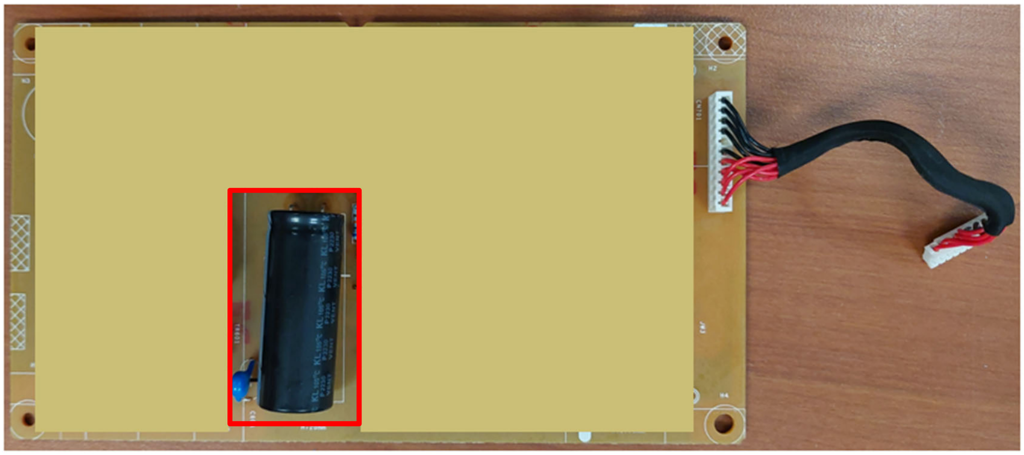


S33 Unlock 1 ground screw and disassemble “WIRE AC+3/3P” from Main SHD

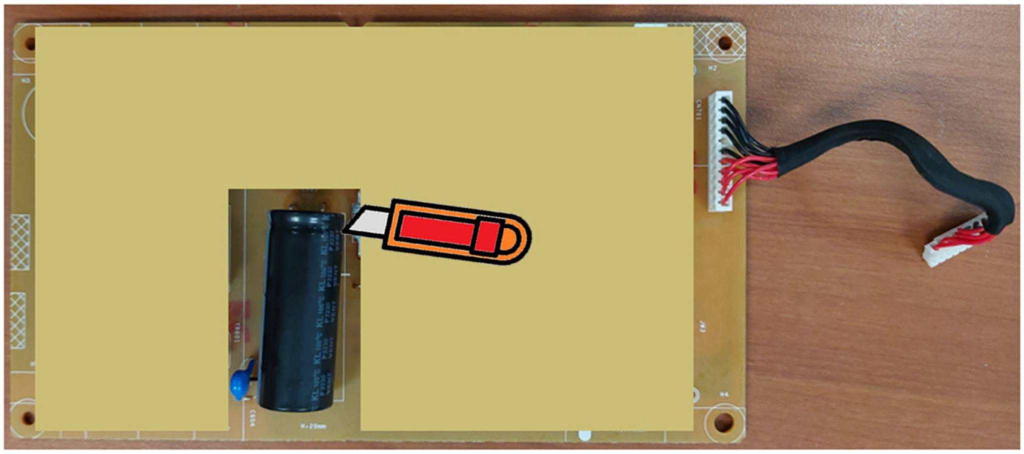


(Screw Torque: 8.5±1 kgf)

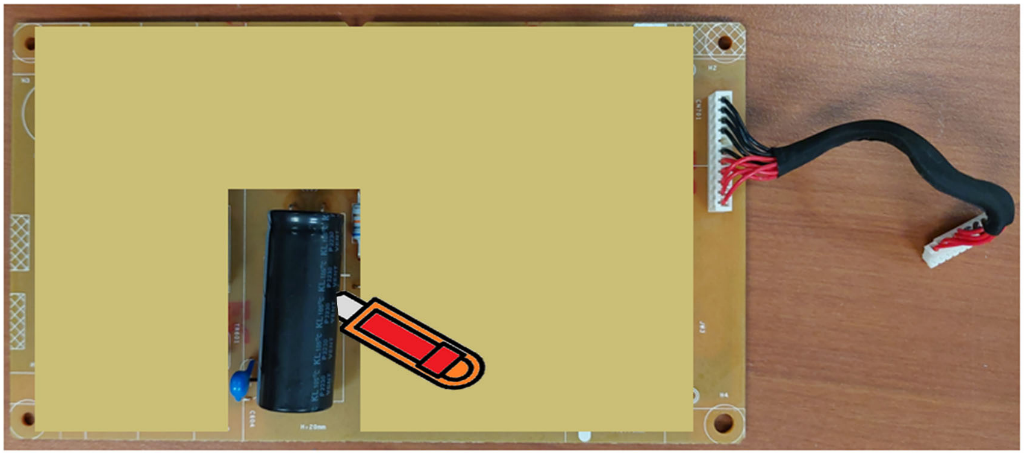
S34 Remove electrolyte capacitors (red mark) from printed circuit boards



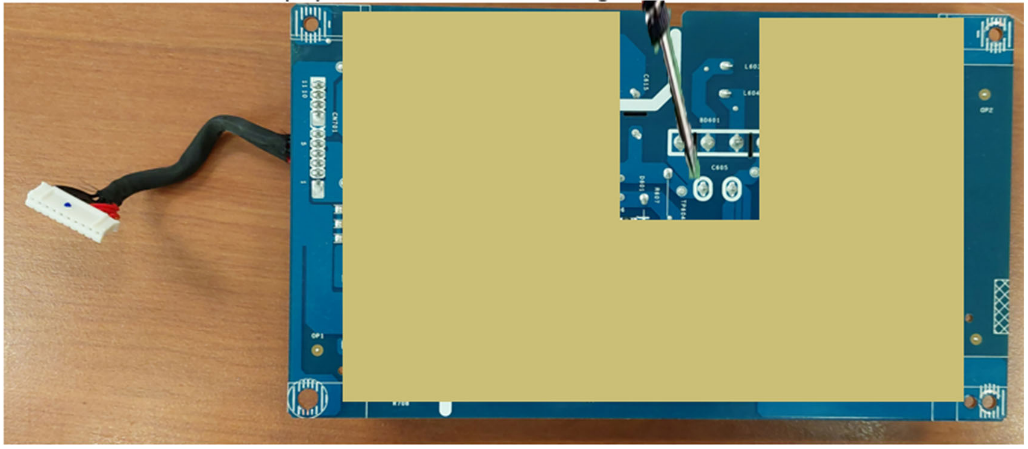
S34-1 Cut the glue between bulk cap. and PCB with a knife



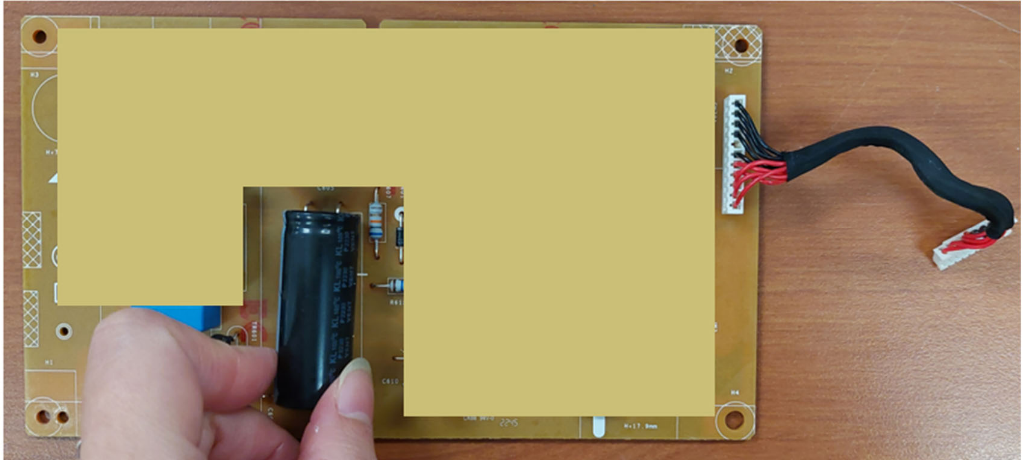
S34-2 Ensure cutting path within the glue, don't touch bulk cap. or PCB



S34-3 Take out bulk cap. pin solder with soldering iron and absorber



S34-4 Lift the bulk cap. up and away from the PCB



2. Product material information

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

Capacitors / condensers (containing PCB/PCT)	No used
Mercury containing components	No used
Batteries	No used
Printed circuit boards (with a surface greater than 10 square cm)	Product has printed circuit boards (with a surface greater than 10 square cm)
Component contain toner, ink and liquids	No used
Plastic containing BFR	No used
Component and waste contain asbestos	No used
CRT	No used
Component contain CFC, HCFC, HFC and HC	No used
Gas discharge lamps	No used
LCD display > 100 cm2	Product has an LCD greater than 100 cm2
External electric cable	Product has external cables
Component contain refractory ceramic fibers	No used
Component contain radio-active substances	No used
Electrolyte capacitors (height > 25mm, diameter > 25mm)	Product has electrolyte capacitors (height >25mm, diameter > 25mm)

3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.
Tool Description:

- Screwdriver
- Scraper Bar
- Penknife
- Soldering iron and absorber